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12/15/99

December 15, 1999

Docket No.: AB-881 US

Box Patent Application
Assistant Commissioner for Patents
Washington, D. C. 20231

Enclosed herewith for filing is a patent application, as follows:

Inventors: Kwon, Heung-Kyu; Cho, Min-Kyo

Title: Semiconductor Chip Package And Method Of Fabricating The Same

X Return Receipt Postcard
X This Transmittal Letter (in duplicate)
2 page(s) Declaration For Patent Application and Power of Attorney
8 page(s) Specification and Title Page (not including claims)
4 page(s) Claims
1 page Abstract
4 Sheet(s) of Drawings
1 page(s) Recordation Form Cover Sheet (in duplicate)
1 page(s) Assignment
☒ Certified Copy of Korean Patent Application No. 1998-54972 filed December 15, 1998

CLAIMS AS FILED (fees computed under §1.9(f))

For	Number	Number	Basic Fee
	<u>Filed</u>	<u>Extra</u>	
Total Claims	20	-20 = 0	\$ 760.00
Independent Claims	3	-3 = 0	\$ 0.00
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<input type="checkbox"/> Application contains one or more multiple dependent claims (total fee)			\$
<input type="checkbox"/> Fee for Request for Extension of Time			\$

Please make the following charges to Deposit Account 19-2386:

- ☒ Total fee for filing the patent application in the amount of \$ 760.00
☒ The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account 19-2386.

EXPRESS MAIL LABEL NO:

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Respectfully submitted,

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